Reset Command for SpiStack®

INTRODUCTION

The W25M ***SpiStack***® series Flash memory is based on the popular ***SpiFlash***® series by stacking serial NOR and serial NAND into a standard 8-pin package. It offers flexible memory density and reliability combination for the low pin-count package, as well as Concurrent Operations in Serial Flash memory for the first time. The W25M ***SpiStack***® series is ideal for small form factor system designs, and applications that demand high Program/Erase data throughput.

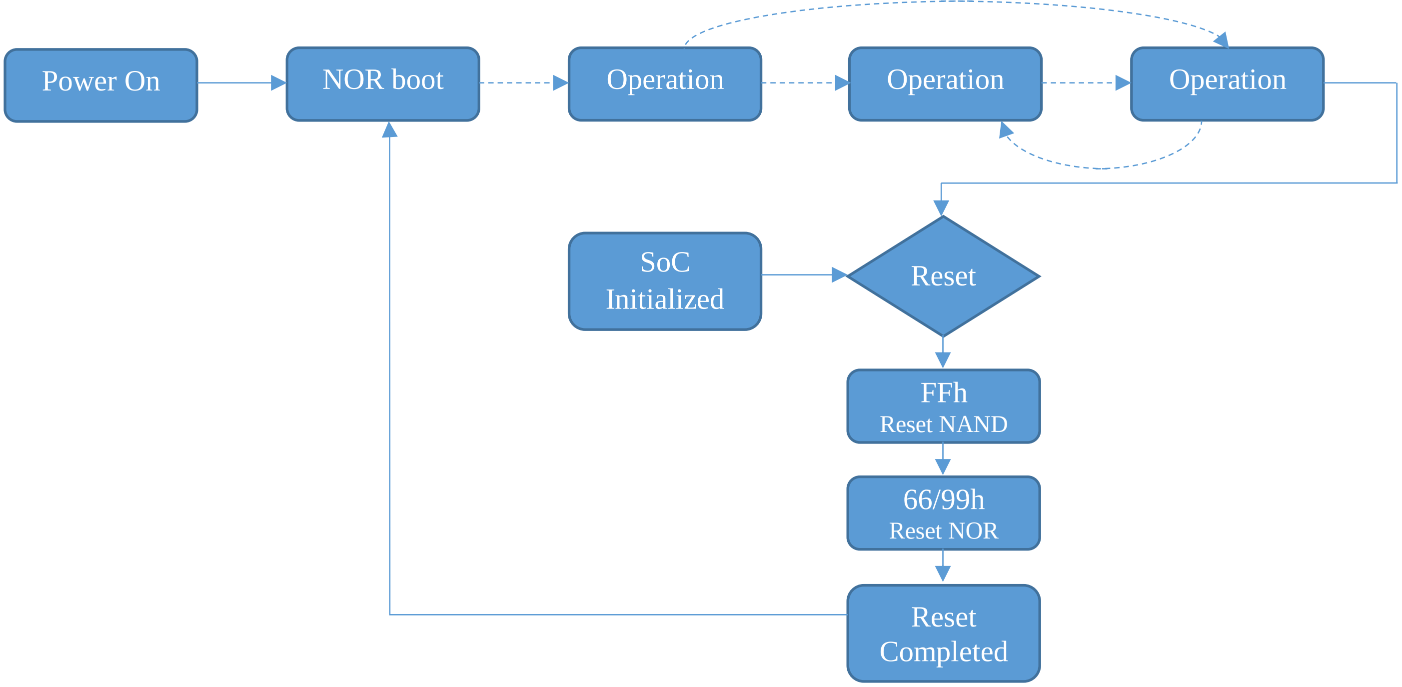
The ***SpiStack***® product series introduces a new “Software Die Select (C2h)” instruction, and a factory assigned “Die ID#” for each stacked die. Each die can be accessed independently even though the interface is shared. The ***SpiStack***® feature only allows a single die to be Active and have control of the SPI interface at any given time to avoid bus contention.

Since the reset command of serial NOR and serial NAND is different. This application note indicates the recommended reset command sequence during the operation of ***SpiStack***® series Flash memory.

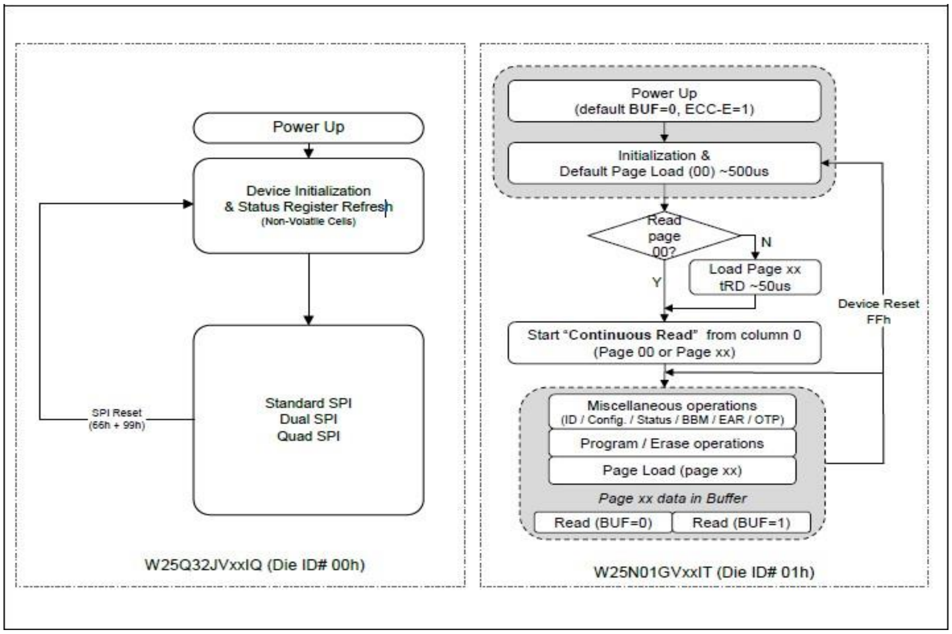
RECOMMAND SOFTWARE RESET SEQUENCE AFTER POWER UP

The ***SpiStack***® device supports two different software Reset instruction for each die instead of a dedicated RESET pin due to the limitation of its 8-pin count small packages. Although only a single die is active and have the control of the SPI bus to communicate with the external SPI controller at any given time, the dice will be able to accept the valid software reset instruction despite their Active or Idle status.

To prevent unexpected die selection after reset, it is recommended to issue full reset command set of NAND and NOR (FFh+66/99h) to reset the SpiStack® device. And also, it is recommended to do the reset procedure even there is no power down but only do the SoC initialized sequences.



For more details on software reset functionality, refer to the ***SpiStack***® data sheets.



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Revision History

Version	Date	Page	Description
1.0	01/06/2017	NA	Initial Version
2.0	12/15/2017	NA	Converted to the new Application Note format.

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